NTS10100MFS, NRVTS10100MFS

Very Low Forward Voltage Trench-based Schottky Rectifier

ON Semiconductor®

SCHOTTKY BARRIER RECTIFIERS
10 AMPERES
100 VOLTS

Features

- Fine Lithography Trench−based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- Low Thermal Resistance
- High Surge Capability
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These are Pb−Free and Halide−Free Devices

Typical Applications

- Switching Power Supplies including Notebook / Netbook Adapters, ATX and Flat Panel Display
- High Frequency and DC−DC Converters
- Freewheeling and OR−ing diodes
- Reverse Battery Protection
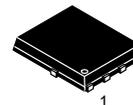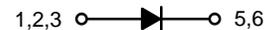- Instrumentation

Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94−0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting SurfaceTemperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

1,2,3 ○—▶|—○ 5,6

SO−8 FLAT LEAD CASE 488AA STYLE 2

MARKING DIAGRAM

TH1010
AYWWZZ

TH1010	= Specific Device Code
A	= Assembly Location
Y	= Year
W	= Work Week
ZZ	= Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping†
NTS10100MFST1G	SO−8 FL (Pb−Free)	1500 / Tape & Reel
NTS10100MFST3G	SO−8 FL (Pb−Free)	5000 / Tape & Reel
NRVTS10100MFST1G	SO−8 FL (Pb−Free)	1500 / Tape & Reel
NRVTS10100MFST3G	SO−8 FL (Pb−Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	 100	V
Average Rectified Forward Current (Rated V_R, T_C = 137°C)	$I_{F(AV)}$	10	A
Peak Repetitive Forward Current, (Rated V_R, Square Wave, 20 kHz, T_C = 134°C)	I_{FRM}	16	A
Non−Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	200	A
Storage Temperature Range	T_{stg}	−65 to +150	°C
Operating Junction Temperature	T_J	−55 to +150	°C
Unclamped Inductive Switching Energy (10 mH Inductor, Non−repetitive)	E_{AS}	100	mJ
ESD Rating (Human Body Model)		3B	
ESD Rating (Machine Model)		M4	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance, Junction−to−Case, Steady State (Assumes 600 mm^2 1 oz. copper bond pad, on a FR4 board)	$R_{\theta JC}$	2.0	−	°C/W

ELECTRICAL CHARACTERISTICS

	Symbol	Typ	Max	Unit
Instantaneous Forward Voltage (Note 1) (i_F = 5 Amps, T_J = 25°C) (i_F = 10 Amps, T_J = 25°C) (i_F = 5 Amps, T_J = 125°C) (i_F = 10 Amps, T_J = 125°C)	v_F	 0.512 0.620 0.450 0.574	 − 0.690 − 0.590	V
Instantaneous Reverse Current (Note 1) (V_R = 70 V, T_J = 25°C) (Rated dc Voltage, T_J = 25°C) (V_R = 70 V, T_J = 125°C) (Rated dc Voltage, T_J = 125°C)	i_R	 7.0 15 4.0 10	 − 70 − 35	 μA μA mA mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
1. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.
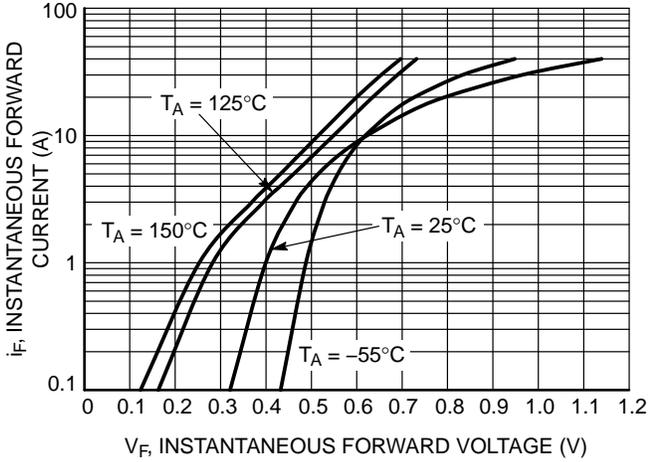
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TYPICAL CHARACTERISTICS

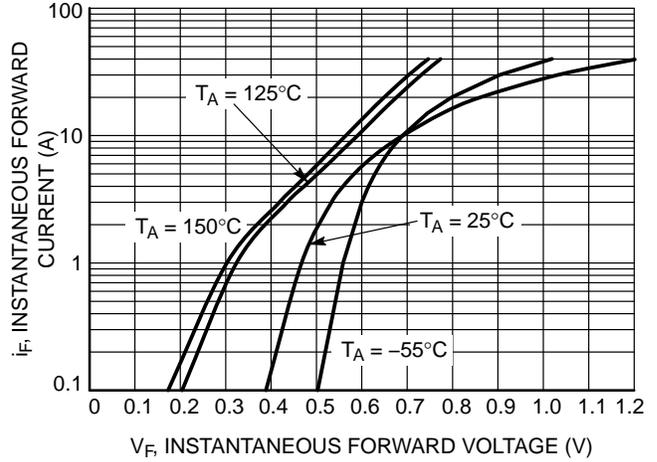**Figure 1. Typical Instantaneous Forward Characteristics**

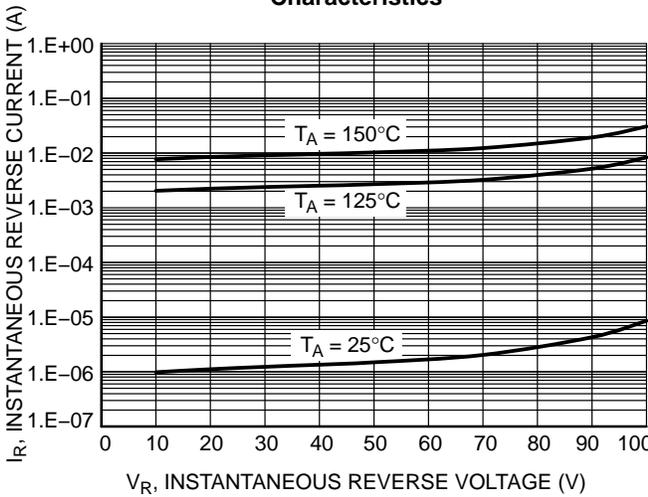**Figure 2. Maximum Instantaneous Forward Characteristics**
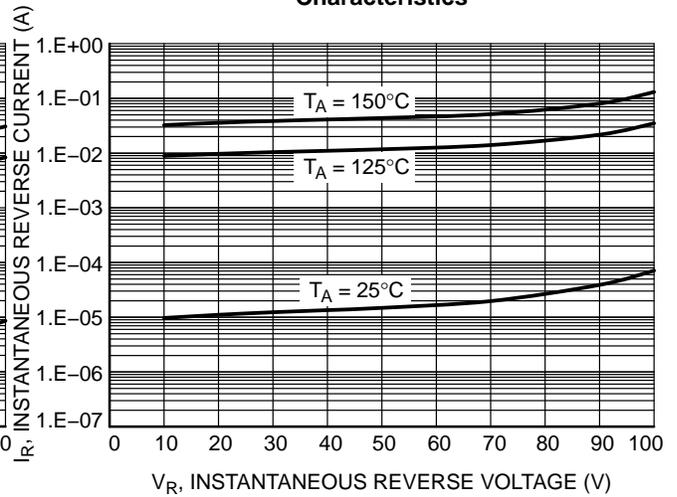

Figure 3. Typical Reverse Characteristics
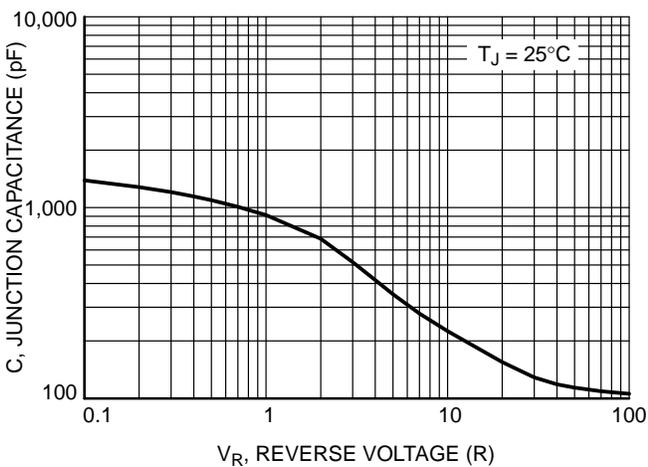

Figure 4. Maximum Reverse Characteristics

Figure 5. Typical Junction Capacitance

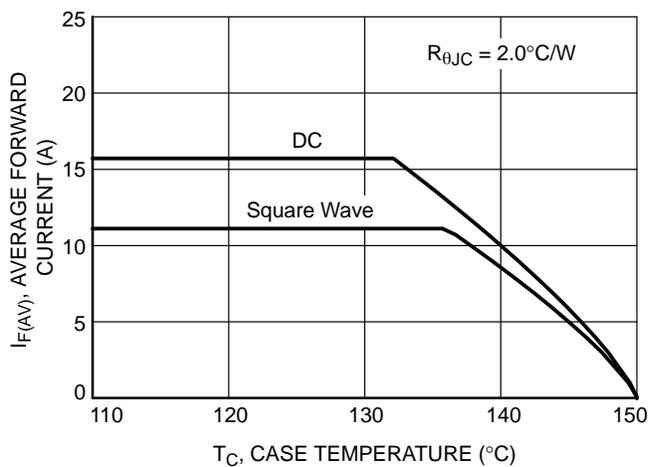**Figure 6. Current Derating**

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TYPICAL CHARACTERISTICS
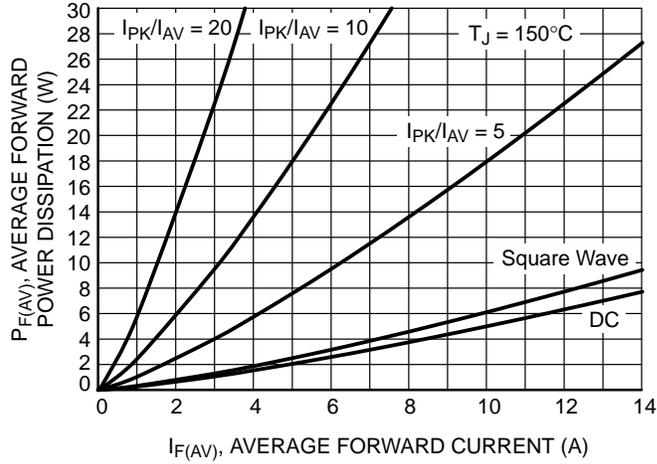
Figure 7. Forward Power Dissipation
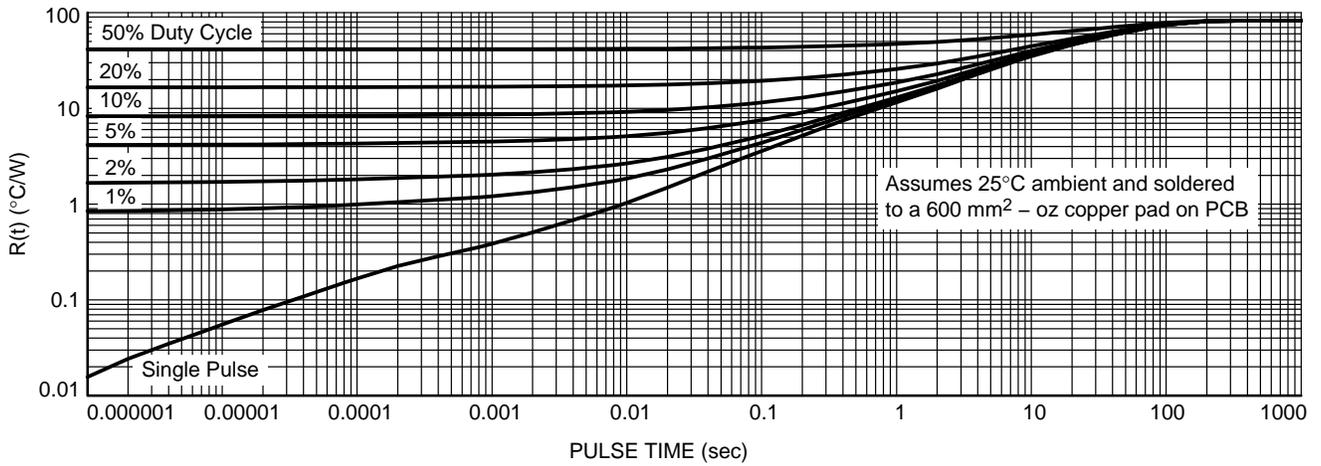
Figure 8. Thermal Characteristics
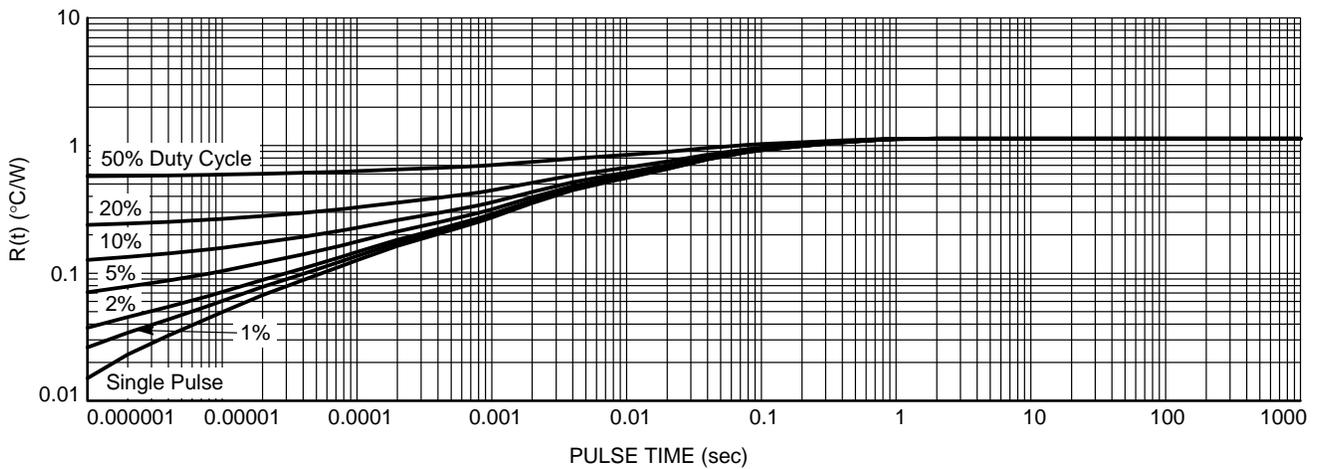
Figure 9. Typical Transient Thermal Response Characteristics, Junction–to–Case

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PACKAGE DIMENSIONS

DFN5 5x6, 1.27P
(SO–8FL)
CASE 488AA
ISSUE G

TOP VIEW

SIDE VIEW

DETAIL A

BOTTOM VIEW

PIN 5
(EXPOSED PAD)

SOLDERING FOOTPRINT*

SEATING PLANE
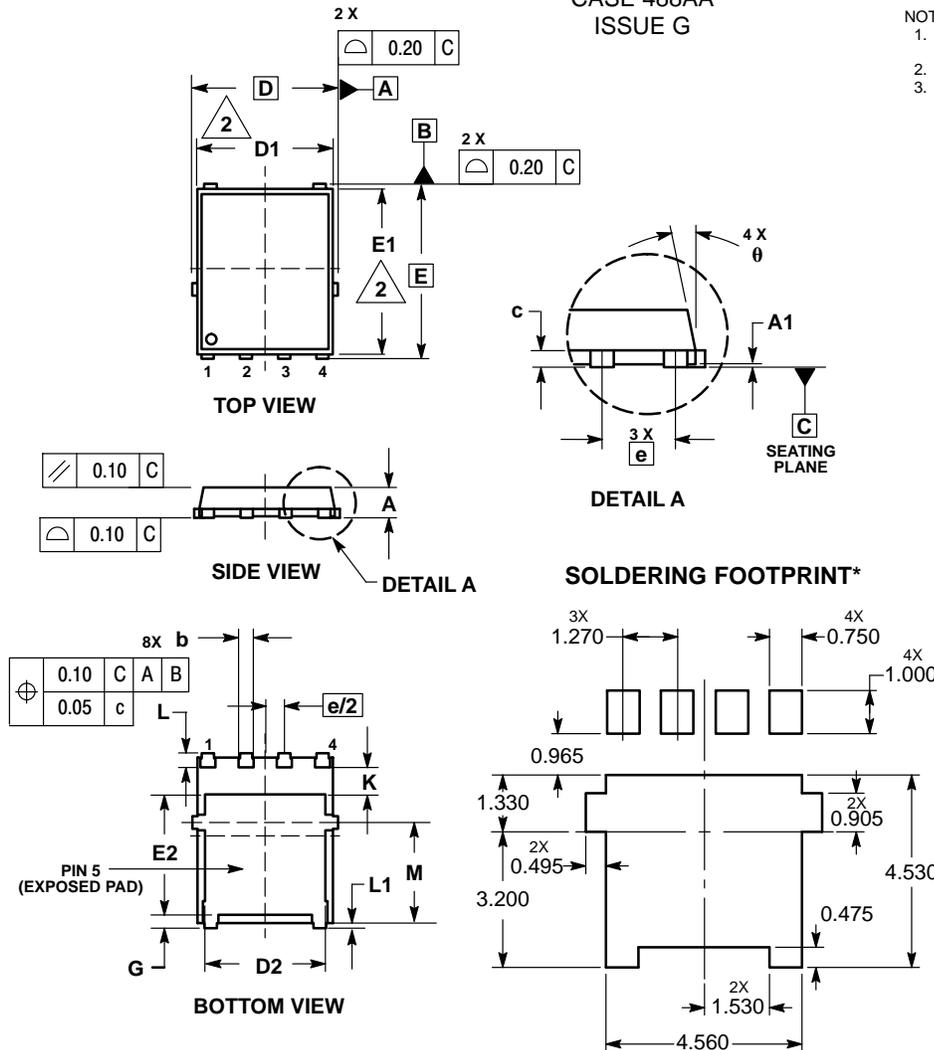
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	–––	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.15 BSC		
D1	4.50	4.90	5.10
D2	3.50	–––	4.22
E	6.15 BSC		
E1	5.50	5.80	6.10
E2	3.45	–––	4.30
e	1.27 BSC		
G	0.51	0.61	0.71
K	1.20	1.35	1.50
L	0.51	0.61	0.71
L1	0.05	0.17	0.20
M	3.00	3.40	3.80
θ	0 °	–––	12 °

STYLE 2:
PIN 1. ANODE
2. ANODE
3. ANODE
4. NO CONNECT
5. CATHODE

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.